

## SLOVENSKI STANDARD SIST EN IEC 62878-2-602:2021

01-oktober-2021

Tehnologija sestavov z vdelanimi elementi - 2-602. del: Smernice za zložene elektronske module - Metode vrednotenja vmesnih modulov električne povezljivosti

Device Embedding assembly technology - Part 2-602: Guideline for stacked electronic module - Evaluation method of inter-module electrical connectivity

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SIST EN IEC 62878-2-602:2021

Ta slovenski standard je istoveten az log stan EN IEC 62878-2-602:2021

#### ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards

plošče

31.190 Sestavljeni elektronski Electronic component

elementi assemblies

SIST EN IEC 62878-2-602:2021 en

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EUROPEAN STANDARD NORME EUROPÉENNE

**EUROPÄISCHE NORM** 

EN IEC 62878-2-602

August 2021

ICS 31.180; 31.190

### **English Version**

Device embedding assembly technology - Part 2-602: Guideline for stacked electronic module - Evaluation method of intermodule electrical connectivity

(IEC 62878-2-602:2021)

Techniques d'assemblage avec appareil(s) intégré(s) -Partie 2-602: Lignes directrices pour un empilement de modules électroniques - Méthode d'évaluation de la connectivité électrique entre modules (IEC 62878-2-602:2021) Montageverfahren für eingebettete Bauteile - Teil 2-602: Leitfaden für gestapelte Elektronikmodule - Verfahren zur Beurteilung der elektrischen Verbindungsfähigkeit zwischen den Modulen (IEC 62878-2-602:2021)

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CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 62878-2-602:2021 (E)

### **European foreword**

The text of document 91/1663/CDV, future edition 1 of IEC 62878-2-602, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62878-2-602:2021.

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EN IEC 62878-2-602:2021 (E)

## Annex ZA (normative)

# Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication Year Title EN/HD Year

IEC 60194-2

- Printed boards design, manufacture andassembly - Vocabulary - Part 2: Common
usage in electronic technologies as well as
printed board and electronic assembly
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IEC 62878-2-602

Edition 1.0 2021-06

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



Device embedding assembly technology D PREVIEW
Part 2-602: Guideline for stacked electronic module – Evaluation method of inter-module electrical connectivity

SIST EN IEC 62878-2-602:2021

Techniques d'assemblage avec appareil(s) intégré(s) = 4b24-b72c-Partie 2-602: Lignes directrices pour un empilement de modules électroniques – Méthode d'évaluation de la connectivité électrique entre modules

INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

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#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### DEVICE EMBEDDING ASSEMBLY TECHNOLOGY -

## Part 2-602: Guideline for stacked electronic module – Evaluation method of inter-module electrical connectivity

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International Standard IEC 62878-2-602 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1663/CDV	91/1720/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
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- replaced by a revised edition, or
- amended.

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